



VOIDLESS HERMETICALLY SEALED FAST RECOVERY GLASS RECTIFIERS

Qualified per MIL-PRF-19500/411

*Qualified Levels:
JAN, JANTX, JANTXV
and JANS*

DESCRIPTION

This "fast recovery" rectifier diode series is military qualified and is ideal for high-reliability applications where a failure cannot be tolerated. These industry-recognized 3.0 amp rated rectifiers for working peak reverse voltages from 50 to 600 volts are hermetically sealed with voidless-glass construction using an internal "Category 1" metallurgical bond. These devices are also available in surface mount MELF package configurations. Microsemi also offers numerous other rectifier products to meet higher and lower current ratings with various recovery time speed requirements including fast and ultrafast device types in both through-hole and surface mount packages.

Important: For the latest information, visit our website <http://www.microsemi.com>.

FEATURES

- Popular JEDEC registered 1N5415 thru 1N5420 series.
- Voidless hermetically sealed glass package.
- Quadruple-layer passivation.
- Internal "Category 1" metallurgical bonds.
- Working Peak Reverse Voltage 50 to 600 volts.
- JAN, JANTX, JANTXV and JANS qualifications available per MIL-PRF-19500/411.
- RoHS compliant versions available (commercial grade only).

APPLICATIONS / BENEFITS

- Fast recovery 3 amp 50 to 600 volt rectifiers.
- Military and other high-reliability applications.
- General rectifier applications including bridges, half-bridges, catch diodes, etc.
- High forward surge current capability.
- Extremely robust construction.
- Low thermal resistance.
- Controlled avalanche with peak reverse power capability.
- Inherently radiation hard as described in Microsemi "MicroNote 050".

MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T_J and T_{STG}	-65 to +175	$^{\circ}\text{C}$
Thermal Resistance Junction-to-Lead ⁽¹⁾	$R_{\theta JL}$	22	$^{\circ}\text{C/W}$
Forward Surge Current @ 8.3 ms half-sine	I_{FSM}	80	A
Average Rectified Forward Current ⁽⁴⁾ @ $T_A = +55^{\circ}\text{C}$ @ $T_A = +100^{\circ}\text{C}$	$I_O^{(2,3)}$	3	A
	$I_O^{(3)}$	2	A
Working Peak Reverse Voltage	V_{RWM}	50	V
1N5415		100	
1N5416		200	
1N5417		400	
1N5418		500	
1N5419		600	
Maximum Reverse Recovery Time ⁽⁵⁾	t_{rr}	150	ns
1N5415		150	
1N5416		150	
1N5417		150	
1N5418		250	
1N5419		400	
Solder Temperature @ 10 s	T_{SP}	260	$^{\circ}\text{C}$

See notes on next page.



"B" Package

Also available in:

**"B" SQ-MELF
(D-5B) Package**
(surface mount)

 [1N5415US - 1N5420US](#)

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MAXIMUM RATINGS

- Notes:**
1. At 3/8 inch (10 mm) lead length from body.
 2. Derate linearly at 22 mA/°C for $55^{\circ}\text{C} \leq T_A \leq 100^{\circ}\text{C}$.
 3. Above $T_A = 100^{\circ}\text{C}$, derate linearly at 26.7 mA/°C to zero at $T_A = 175^{\circ}\text{C}$.
 4. These ambient ratings are for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where $T_{J(\text{max})}$ does not exceed 175°C .
 5. $I_F = 0.5\text{ A}$, $I_{RM} = 1\text{ A}$, $I_{R(\text{REC})} = 0.250\text{ A}$.

MECHANICAL and PACKAGING

- CASE: Hermetically sealed voidless hard glass with tungsten slugs.
- TERMINALS: Axial-leads are tin/lead (Sn/Pb) over copper. RoHS compliant matte-tin is available for commercial grade only.
- MARKING: Body paint and part number.
- POLARITY: Cathode band.
- TAPE & REEL option: Standard per EIA-296. Contact factory for quantities.
- WEIGHT: 750 milligrams.
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE

JAN 1N5415 (e3)

Reliability Level

JAN = JAN Level
JANTX = JANTX Level
JANTXV = JANTXV Level
JANS = JANS Level
Blank = commercial

JEDEC type number

See [Electrical Characteristics](#) table

RoHS Compliance

e3 = RoHS compliant ([available on commercial grade only](#))
Blank = non-RoHS compliant

SYMBOLS & DEFINITIONS

Symbol	Definition
V_{BR}	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.
V_{RWM}	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range excluding all transient voltages (ref JESD282-B).
I_O	Average Rectified Output Current: The Output Current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.
V_F	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
I_R	Maximum Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
t_{rr}	Reverse Recovery Time: The time interval between the instant the current passes through zero when changing from the forward direction to the reverse direction and a specified decay point after a peak reverse current occurs.

ELECTRICAL CHARACTERISTICS

TYPE	MINIMUM BREAKDOWN VOLTAGE	FORWARD VOLTAGE		MAXIMUM REVERSE CURRENT		CAPACITANCE C
	$V_{BR} @ 50 \mu A$	$V_F @ 9 A$		$I_R @ V_{RWM}$		$V_R @ 4 V$
	Volts	MIN. Volts	MAX. Volts	25 °C μA	100 °C μA	pF
1N5415	55	0.6	1.5	1.0	20	550
1N5416	110	0.6	1.5	1.0	20	430
1N5417	220	0.6	1.5	1.0	20	250
1N5418	440	0.6	1.5	1.0	20	165
1N5419	550	0.6	1.5	1.0	20	140
1N5420	660	0.6	1.5	1.0	20	120

NOTE 1: $I_F = 0.5 A$, $I_{RM} = 1 A$, $I_{R(REC)} = 0.250 A$.

GRAPHS

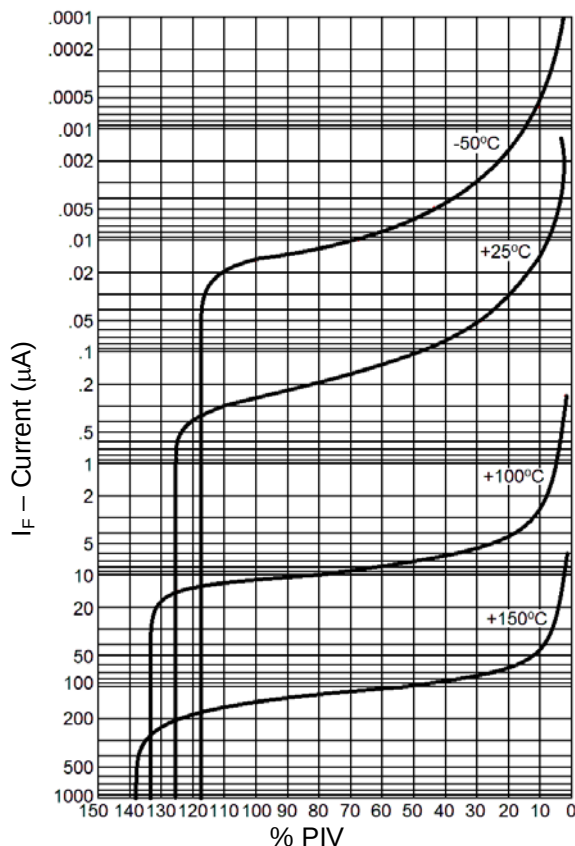


FIGURE 1
Typical Reverse Current vs. PIV

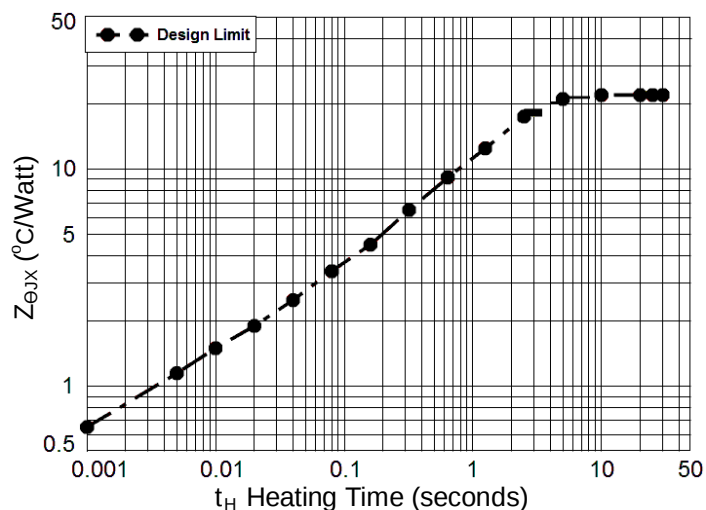


FIGURE 2
Maximum Thermal Impedance

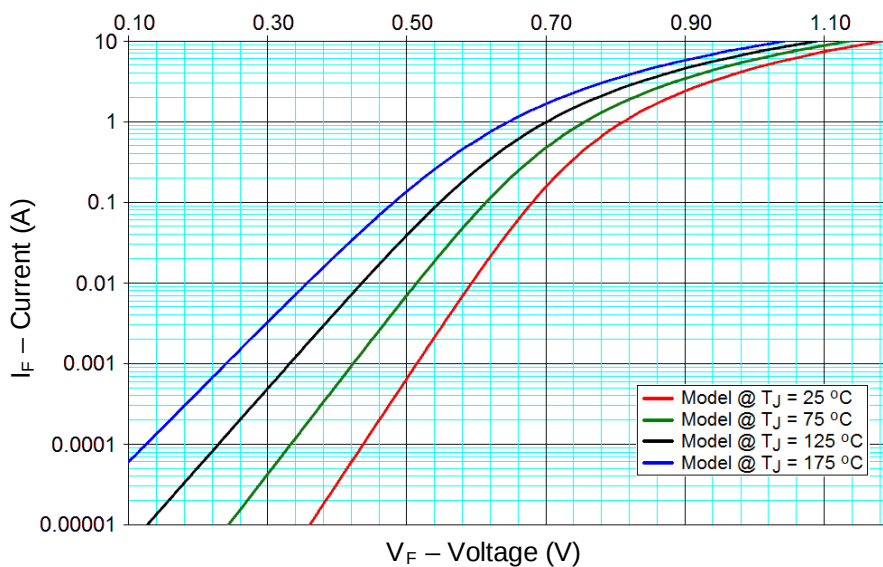
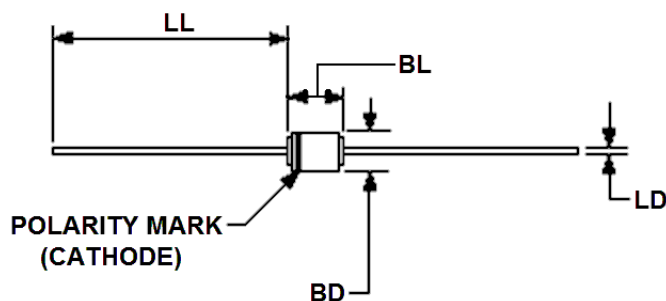


FIGURE 3
Typical Forward Current vs. Forward Voltage

PACKAGE DIMENSIONS



Symbol	Dimensions				Notes
	Inch		Millimeters		
	Min	Max	Min	Max	
BD	0.110	0.180	2.79	4.57	3
LD	0.036	0.042	0.91	1.07	4
BL	0.130	0.260	3.30	6.60	4
LL	0.90	1.30	22.9	33.0	

NOTES:

1. Dimensions are in inches.
2. Millimeter equivalents are given for general information only.
3. Dimension BD shall be measured at the largest diameter.
4. The BL dimension shall include the entire body including slugs and sections of the lead over which the diameter is uncontrolled. This uncontrolled area is defined as the zone between the edge of the diode body and extending .050 inch (1.27 mm) onto the leads.
5. In accordance with ASME Y14.5M, diameters are equivalent to Φ x symbology.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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